

Category	Attributes	2013/2014	2014	2015
FINE LINE / SPACE	INNER LAYERS (LINE / SPACE)	2.5 / 2.5 MIL	2.0 / 2.0 MIL	25 / 25 MICRONS
	OUTER LAYERS (LINE / SPACE)	2.5 / 2.5 MIL	2.0 / 2.0 MIL	25 / 25 MICRONS
HOLES	MECHANICAL (DRILLED HOLE / LAND)	5.9 / 12 MIL	4 / 10 MIL	4 / 6 MIL
	LASER DRILL (DRILLED HOLE / LAND)	4 / 8 MIL	3 / 6 MIL	3 / 6 MIL
SPECIAL PROCESSING	CONTROLLED DEPTH DRILLING - BLIND VIAS	YES	YES	YES
	SEQUENTIAL LAMINATION - BURRIED VIAS	YES	YES	YES
	VIA IN PAD TECHNOLOGY - SILVER EPOXY	YES	YES	YES
	VIA IN PAD TECHNOLOGY - NON CONDUCTIVE	YES	YES	YES
	EDGE PLATING	YES	YES	YES
THRU VIA HOLES	MINIMUM PAD SIZE	8 MIL	8 MIL	8 MIL
	REGISTRATION TO INTERNAL LAND	+5.0 MIL	+4.5 MIL	+4 MIL
	MAXIMUM COPPER PLATING ASPECT RATIO	25:1	25:1	27:1
	MINIMUM FEATURE TO EDGE	5 MIL	5 MIL	5 MIL
PCB / PANEL	MAXIMUM LAYER COUNT	50 LAYERS	60 LAYERS	60 LAYERS +
	MAXIMUM THICKNESS	0.42"	0.62"	0.90"
	MAXIMUM PROCESS PANEL SIZE	24" X 30"	24" X 30"	24" X 30"
IMPEDANCE	SINGLE ENDED & DIFFERENTIAL PAIR TOLERANCE	+4%	+3%	+2%
EMBEDDED PASSIVES	RESISTORS	+20%	+15%	+10%
	CAPACITANCE / CAPACITORS	2 MIL CORE	1 MIL CORE	THIN FILM
SURFACE FINISH	HASL, LEAD FREE HASL, ENIG, IMMERSION TIN,	YES	YES	YES
	IMMERSION SILVER, OSP, CARBON INK,	YES	YES	YES
	ELECTROLYTIC HARD & SOFT GOLD,	YES	YES	YES
	PALLADIUM, NICKEL	YES	YES	YES
CERTIFICATIONS	ISO9000, ISO14001, IPC 6013 CLASS 1, 2 & 3,	YES	YES	YES
	TL9000, QS9000, TS16949, MIL-PRF-31032,	YES	YES	YES
	MIL-PRF-55110, MIL-P-50884, U.L.	YES	YES	YES
REGISTRATIONS	I.T.A.R.	YES	YES	YES